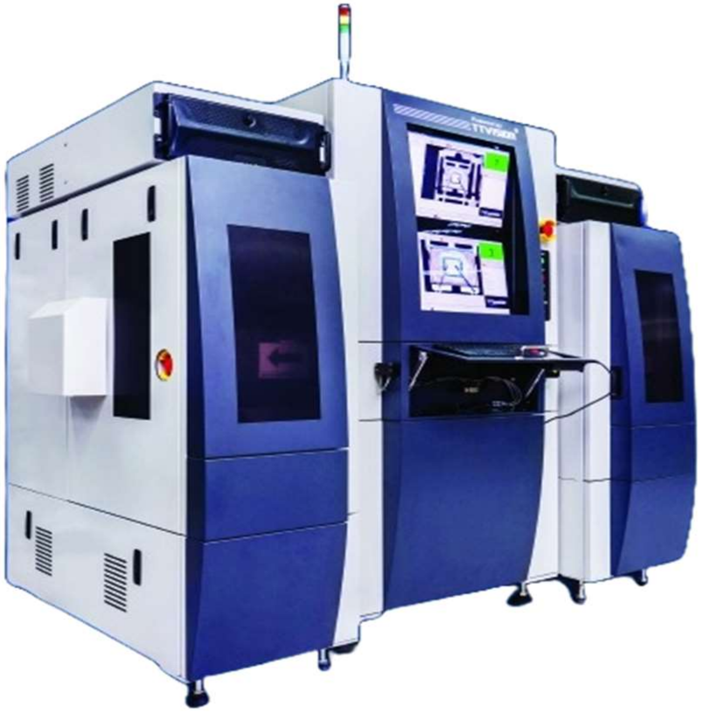
Automated Optical Inspection



cutting-edge AOI for inspecting critical components in semiconductor manufacturing.

Detailed and accurate inspection of wirebond, die, and epoxy features for enhanced defect detection.

High-Resolution Imaging up to 67 megapixels, ensuring high-quality imaging for precise inspection and analysis.

Inspects wirebonds made from various materials, including gold, aluminum, copper, and silver.

Precisely measures essential parameters such as ball, wedge, stitch, and loop characteristics.

Capable of detecting various defects in wirebond connections, die attachment, and epoxy application.

Achieves an accuracy of up to 2.7 micrometers per pixel, ensuring reliable inspection results even for minute features.